Filename: PMP5722RevH - BoM.xls
Date: 1/13/2015

PMP5722RevH - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	B1	BH800S	Battery, Coins CR/BR 2025, 2032	1.075 dia.	BH800S	Memory Protection Devices
1	U1	bq24050	IC, 750mA, Single Cell Li-Ion Battery Charger	SON-10	bq24050/2DSQ	Texas Instruments
1	U4	bq27410	IC, System-Side Impedance Track Fuel Gauge	QFN12	BQ27410DRZ-G1	Texas Instruments
1	C4	100nF	Capacitor, Ceramic, 16V, X7R, 10%	402	Std	Std
4	C6-7 C9-10	100nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C11-12	10pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
1	C19	1nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
4	C3 C16-18	1uF	Capacitor, Ceramic, 10V, X5R, 10%	603	Std	Std
4	C13-15 C20	220nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
3	C1-2 C5	4.7uF	Capacitor, Ceramic, 10V, X5R, 15%	603	Std	Std
1	C8	470nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	J4	67068-1000	Connector, USB Upstream (Type B)	0.47 x 0.67 inch	67068-1000	Molex
1	D2	MA2SD1000L	Diode, Schottky, 200mA, 20V	0.047 x 0.031 inch	MA2SD1000L	Panasonic
4	D3-6	green	Diode, LED, green, 2.1V, 30mA	603	LTST-C190GKT	Lite On
1	D1	yellow	Diode, LED, yellow, 2.1V, 20mA	603	LTST-C190YKT	Lite On
4	D7-10	yellow	Diode, LED, yellow, 2.1V, 20mA	603	LTST-C190GYT	Lite On
2	J1-2	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
2	J5-6	PEC04SAAN	Header, Male 4-pin, 100mil spacing,	0.100 inch x 4	PEC04SAAN	Sullins
1	J3	PEC04DAAN	Header, Male 2x4-pin, 100mil spacing	0.20 x 0.40 inch	PEC04DAAN	Sullins
1	U7	MSP430F5510	IC, Mixed Signal Microcontroller	QFN-48	MSP430F5510IRGZR	Texas Instruments
1	Y1	4MHz	Piezoelectronic, SMT 12 mm	2X4.5 mm	CSTCR4M00G15L99	muRata
1	R4	2.21k	Resistor, Chip, 1/16W, 1%	402	Std	Std
1	R1	221	Resistor, Chip, 1/16W, 1%	402	Std	Std
1	R38	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R28	1.00M	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R12 R15	1.00k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R33	1.40k	Resistor, Chip, 1/16W, 1%	603	Std	Std
3	R2 R26-27	10.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R30	100	Resistor, Chip, 1/16W, 1%	603	Std	Std
3	R5 R19-20	100k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R11	15.4k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	2.00k	Resistor, Chip, 1/16W, 1%	603	Std	Std
7	R29 R31-32 R34-37	2.32k	Resistor, Chip, 1/16W, 1%	603	Std	Std

1	R3	2.87k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R24-25	27.4	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R9 R18 R21 R23	33.2k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R6	34.8k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	4.02k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R39	47.5k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R14	549	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	6.34k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R13	6.81k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R17	120m	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R22	7.32k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R16	25m	Resistor, Chip,1/2W, 1%	1210	Std	Std
1	U2	bq29707	IC, Battery Protection, 1 Cell	WSON	BQ29707DSER	Texas Instruments
1	S1	7914G-1-000E	Switch, 1P1T, PB Momentary, 100-mA, SM	0.19 x 0.18 inch	7914G-1-000E	Bourns
1	U6	TLV70033	IC, 150mA, Low IQ, LDO Regulator	SON-6	TLV70033DSE	Texas Instruments
1	U5	TPD4S012	IC, 4-Chan ESD-Protection Array	USON	TPD4S012DRYR	Texas Instruments
1	U3	TPS2113A	IC, Auto Switching Power Mux, 84mOhm	SON	TPS2113ADRB	Texas Instruments
2	Q3-4	2N7002	MOSFET, N-ch, 60-V, 115-mA, 1.2-Ohms	SOT23	2N7002	Diodes
1	Q1	AON5802B	MOSFET, Dual NFET Switching	HWSON	AON5820B	Alpha & Omega

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